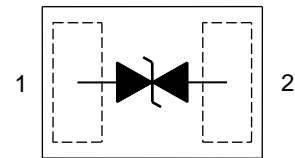


Features

- ◆ low Capacitance 10pF
- ◆ Low Clamping Voltage
- ◆ Small Body Outline Dimensions: 0.039” x 0.024”
(1.0 mm x 0.60 mm)
- ◆ Low Body Height: 0.019” (0.5 mm)
- ◆ Stand-off Voltage: 3.3V
- ◆ Low Leakage
- ◆ Response Time is Typically < 1 ns
- ◆ IEC61000-4-2 Level 4 ESD Protection for data lines
- ◆ These are Pb-Free Devices

DFN1006



Applications

- ◆ 10/100/Mbits/s Ethernet
- ◆ FireWire
- ◆ Display ports
- ◆ MDDI ports
- ◆ Digital Visual Interface (DVI)
- ◆ Cellular handsets & accessories
- ◆ Computer and peripherals

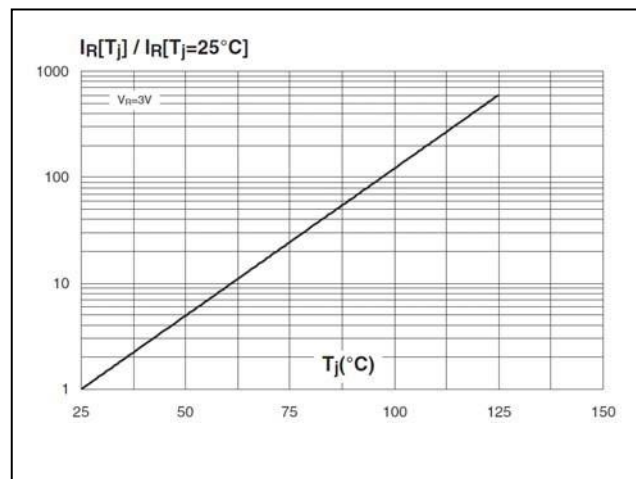
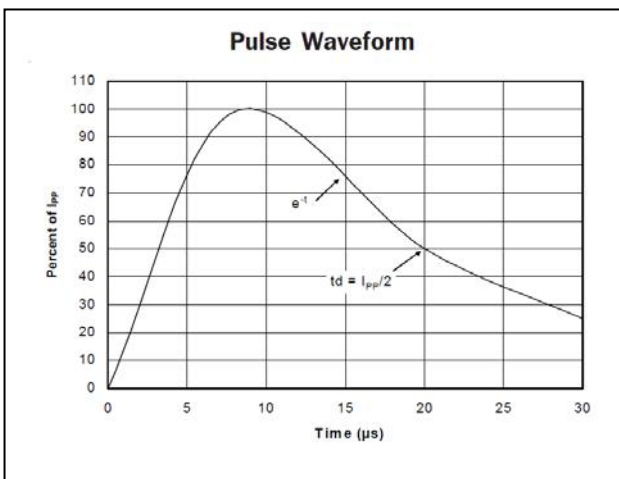
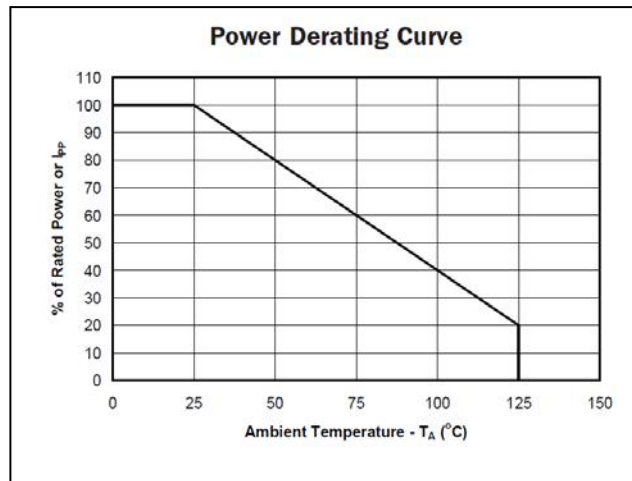
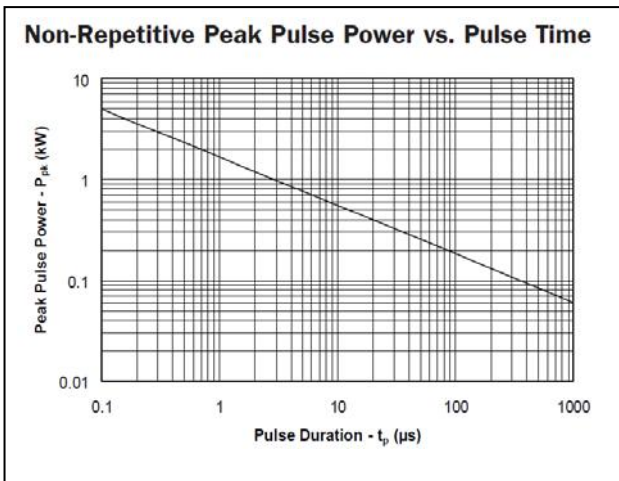
Maximum Rating @ Ta=25°C unless otherwise specified

| Symbol | Parameter | Ratings | Units |
|------------------|----------------------------|-------------|-------|
| ESD | IEC 61000-4-2 (HBM-ESD) | Contact | 8 |
| | | Air | 15 |
| T _L | Lead Soldering Temperature | 260(10sec.) | °C |
| T _J | Operating Temperature | -55 to +125 | °C |
| T _{STG} | Storage Temperature | -55 to +150 | °C |

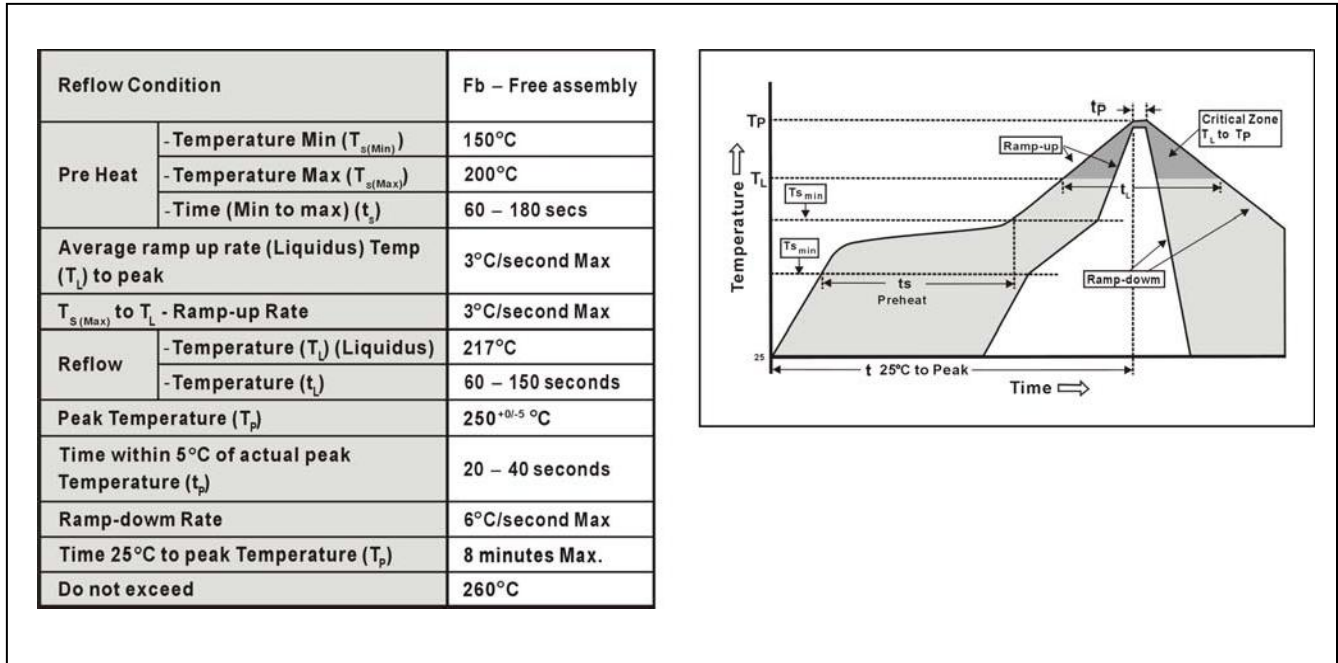
Electrical Characteristics @ Ta=25°C unless otherwise

| Parameter | VRWM @IR | | VBR@ImA | VC@1A | VC@IPP | | CJ |
|---------------|----------|-----|---------|-------|--------|---|-----|
| | V | μA | V | V | V | A | pF |
| | | MAX | MIN | MAX | MAX | | TYP |
| PESDNC2FD3V3B | 3.3 | 1 | 5.0 | 7 | 10 | 5 | 15 |

Typical Characteristics @ Ta=25°C unless otherwise specified



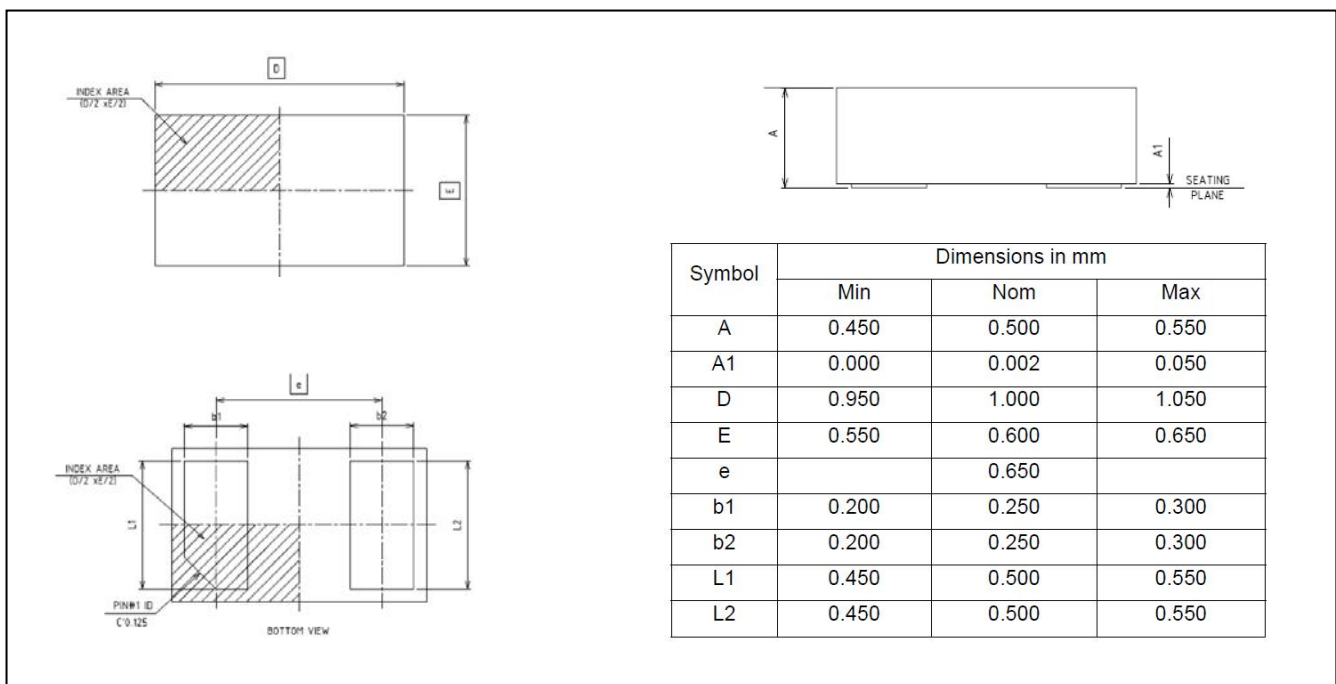
Soldering Parameters



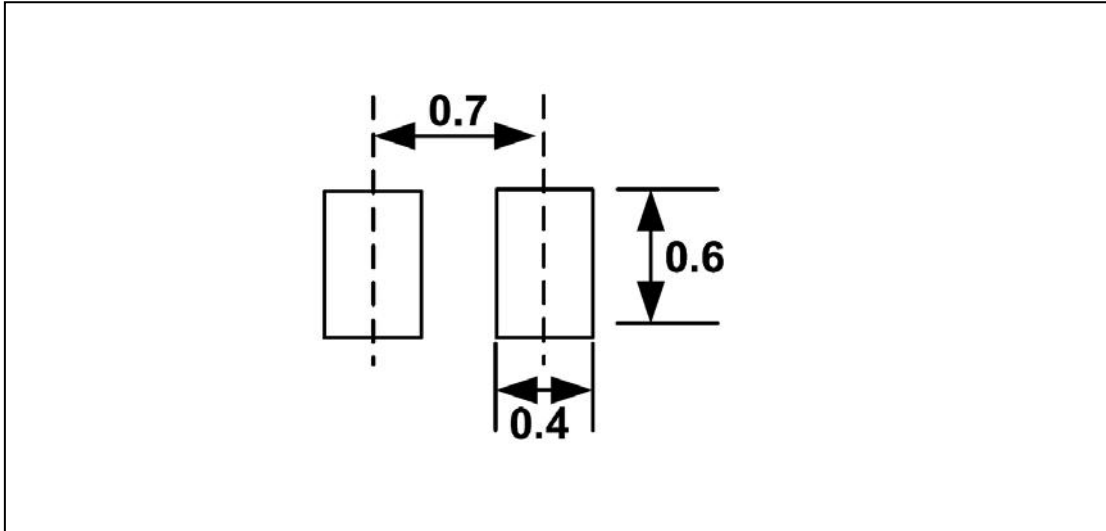
Package Outline

Plastic surface mounted package

DFN 1006-2L



Soldering Footprint



Package And Marking Information

| Device | Package | Shipping | Reel Size |
|--------|------------|----------|-----------|
| TAPING | DFN1006-2L | 10K/Reel | 7 inch |